

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	43	ryuichi.in. and shinkawa.asn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 17:18
L9	5	ryuichi.in. and shinkawa.asn. and telecentric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 17:24
L10	1	ryuichi.in. and shinkawa.asn. and magnification	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 17:35
L11	4	ryuichi.in. and shinkawa.asn. and inclination	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 17:53
L12	8	offset and shinkawa.asn. and inclination	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 17:53
S44	6356	((29/832) or (29/833) or (29/834) or (29/835) or (29/836) or (29/837) or (29/838) or (29/839) or (29/840) or (29/841)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S45	408	(156/358).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S46	5341	156/64.ccls. 156/35\$.ccls. 156/36\$.ccls. 156/37\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24

S47	5341	156/64.ccls. or 156/35\$.ccls. or 156/36\$.ccls. or 156/37\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S48	2078	(calibrate.ti. or calibration.ti.) and (chip or semiconductor or wafer or LCD or DVD)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S49	6318	(maintenance) and (chip or semiconductor or wafer or LCD or DVD)	JPO; DERWENT	OR	ON	2004/10/25 17:24
S50	1186	(maintenance) and (chip)	JPO; DERWENT	OR	ON	2004/10/25 17:24
S52	1086	akira and yamauchi	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S53	440	(156/351).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 18:09
S55	1	("6582991").PN.	USPAT; USOCR	OR	OFF	2004/10/25 17:24
S56	1	("5225026").PN.	USPAT; USOCR	OR	OFF	2004/10/25 17:24
S57	1334	(156/64).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S58	29	(156/64.ccls. or 156/35\$.ccls. or 156/36\$.ccls. or 156/37\$.ccls.) and (calibrate or calibration) and (chip or semiconductor or wafer or LCD or DVD)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S59	4	(156/64.ccls. or 156/35\$.ccls. or 156/36\$.ccls. or 156/37\$.ccls.) and (calibrate or calibration) and (die same (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S60	23	"156"/\$.ccls. and (calibrate or calibration) and (die same (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 18:16

S61	771	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 18:30
S62	0	S61/\$.ccls. and (calibrate or calibration) and (die near10 (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S63	3	S61/\$.ccls. and (calibrate or calibration) and (chip or semiconductor or wafer or LCD or DVD)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S64	14	(calibrate.ti. or calibration.ti.) and (die near10 (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 14:49
S65	97	(calibrate.ti. or calibration.ti.) and (chip or semiconductor or wafer or LCD or DVD) and (bonding or bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S66	191	(702/95).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S67	196	(700/254).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S68	18	(calibrate.ti. or calibration.ti.) and (chip near10 (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S69	2	"2000269241"	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S71	1	JP11070230	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S72	1	jp2000227367	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S73	18	(maintenance) and (chip) and (camera)	JPO; DERWENT	OR	ON	2004/10/25 17:24

S74	99	(maintenance) and (chip) and (temperature)	JPO; DERWENT	OR	ON	2004/10/25 17:24
S75	7	akira and yamauchi and calibrat\$	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S76	42	toray and calibrat\$	JPO; DERWENT	OR	OFF	2004/10/25 17:24
S77	97	(calibrat\$) and (chip) and (temperature)	JPO; DERWENT	OR	ON	2004/10/25 17:24
S78	34	((((29/740) or (29/741) or (29/742) or (29/743)).CCLS.) and (calibrat\$) and (chip or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 17:24
S79	431	(29/833).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S83	12126	application near10 "371"	USPAT	OR	OFF	2004/10/25 17:24
S84	1	("5225026").PN.	USPAT; USOCR	OR	OFF	2004/10/25 17:24
S85	841	("0029832").PN. or ((29/833) or (29/834)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/25 17:24
S86	252	"156"/\$.ccls. and (offset) and (die same (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 18:18
S87	2	"156"/\$.ccls. and (offset near4 camera) and (die same (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 18:31
S88	2	"156"/\$.ccls. and (offset near4 camera) and (semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 14:10
S89	2	"156"/\$.ccls. and (offset near4 camera) and (semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/25 18:20

S90	7	"29"/\$.ccls. and (offset near4 camera) and (semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 14:11
S91	59	(offset.ti.) and (die near10 (bond or bonding or bonder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 14:50
S92	336	(156/362).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 14:54
S93	2798	((29/740) or (29/741) or (29/742) or (29/743)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 16:42
S94	6364	((29/832) or (29/833) or (29/834) or (29/835) or (29/836) or (29/837) or (29/838) or (29/839) or (29/840) or (29/841)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 16:52
S95	17	(S93 or S94) and (camera near10 offset)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 17:28
S96	771	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 17:28
S97	3	S96 and (camera near10 offset)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 17:30
S98	220	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/26 18:30

S99	6	"156"/\$.ccls. and (offset near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 11:08
S100	22	"29"/\$.ccls. and (offset near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 19:19
S101	17	(telecentric near5 (lens or len)) and (offset near4 camera) and (position\$4 near4 camera) and (align or alignment or calibrate or calibration or aligning or calibrating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:40
S102	2	(telecentric near5 (lens or len)) same (offset near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:42
S103	4	(telecentric near5 (lens or len)) same (calibrat\$4 near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:42
S104	0	(tele-centric near5 (lens or len)) same (calibrat\$4 near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:42
S105	0	(tele-centric near5 (lens or len)) same (offset near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:51
S106	12	(inclination) same (offset near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/26 20:51
S107	2	"156"/\$.ccls. and ((telecentric or tele-centric) near4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 11:09
S108	6	"156"/\$.ccls. and ((telecentric or tele-centric) near4 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/27 11:10

S10 9	2	("6649893").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 11:10
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